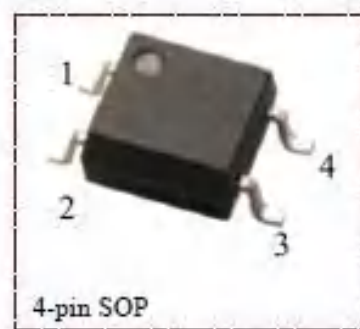
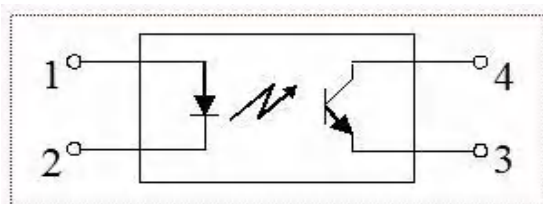


说明

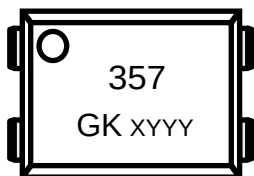
EL357是一款小外形的贴片光电耦合器件，适合表面贴装生产。EL357 是由一个砷化镓发光二极管和一个光电晶体管组成的光电耦合器，它的体积比 DIP 小，适用于高密度表面贴装应用，如可编程控制器等。

应用范围

- 开关电源，智能电表
- 工业控制，测量仪器
- 办公设备，比如复印机
- 家用电器，比如空调、风扇、热水器等



Marking



- The "x" in the printed word represents the product segment: A、B、C、D or others
印字中的“x”代表产品 CTR 分档：A、B、C、D 等
- The "YYY" represents the traceability code
印字中“YYY”代表溯源码
- The "GK" in the printed word represents the product brand
印字中的“GK”代表产品品牌

最大绝对额定值（常温=25℃）

参数		符号	额定值	单位
输入	正向电流	I_F	50	mA
	正向脉冲电流	I_{FP}	1	A
	反向电压	V_R	6	V
	功耗	P	70	mW
	结温	T_j	125	°C
输出	集电极功耗	P_C	150	mW
	集电极电流	I_C	50	mA
	集电极-发射极电压	V_{CE0}	80	V
	发射极-集电极电压	V_{ECO}	7	V
	结温	T_j	125	°C
总功耗		P_{tot}	200	mW
隔离电压		V_{iso}	5000	V_{rms}
工作温度		T_{opr}	-55~+110	°C
储存温度		T_{stg}	-55~+125	°C
焊接温度		T_{sol}	260	°C

光电特性 (常温=25℃)

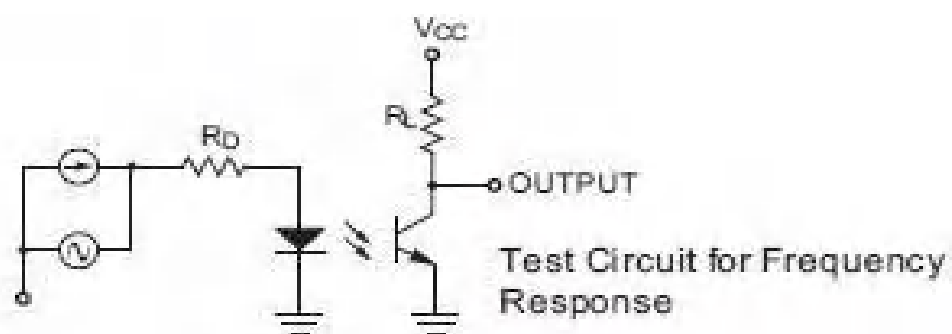
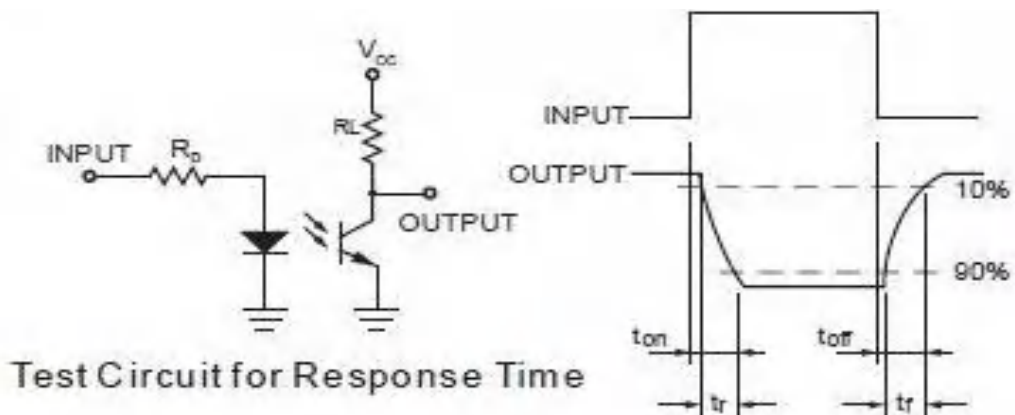
Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
输入	正向电压	V_F	$I_F=20\text{mA}$		1.2	1.4	V
	反向电流	I_R	$V_R=5\text{V}$	-	-	10	μA
	终端电容	C_t	$V=0, f=1\text{kHz}$	-	30	250	pF
输出	集电极暗电流	I_{CEO}	$V_{CE}=70\text{V}$	-	-	100	nA
	集电极-发射极击穿电压	BV_{CEO}	$I_C=0.1\text{mA}, I_F=0$	80	-	-	V
	发射极-集电极击穿电压	BV_{ECO}	$I_E=0.1\text{mA}, I_F=0$	7	-	-	V
传输特性	电流转换比	CTR	$I_F=5\text{mA}, V_{CE}=5\text{V}$	50	-	400	%
	饱和压降	$V_{CE(sat)}$	$I_F=20\text{mA}, I_C=1\text{mA}$	-	0.1	0.2	V
	集电极-发射极饱和压降	R_{ISO}	DC1000V, 40~60%R.H.	1×10^{11}	-	-	Ω
	隔离电容	C_f	$V=0, f=1\text{MHz}$	-	0.6	1.0	pF
	集电极-发射极电容	C_{CE}	$V=0, f=1\text{MHz}$		10		pF
	截止频率	F_c	$V_{CE}=5\text{V}, I_C=2\text{mA},$ $R_L=100\Omega, -3\text{dB}$	-	80	-	kHz
开关时间	上升时间	T_r	$V_{CE}=10\text{V}, I_C=2\text{mA},$ $R_L=100\Omega$	-	4	18	μs
	下降时间	T_f		-	3	18	μs

电流转换比 (CTR) 的等级分类

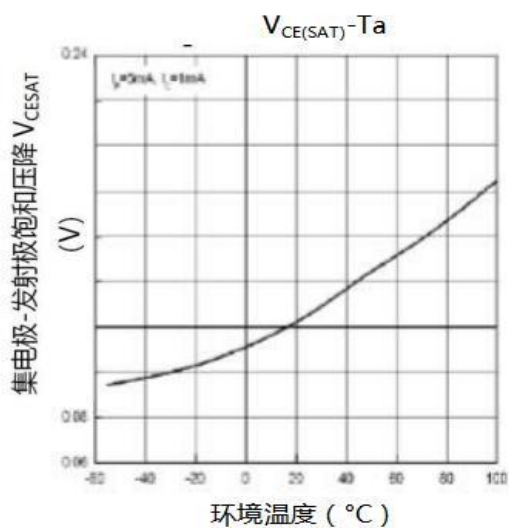
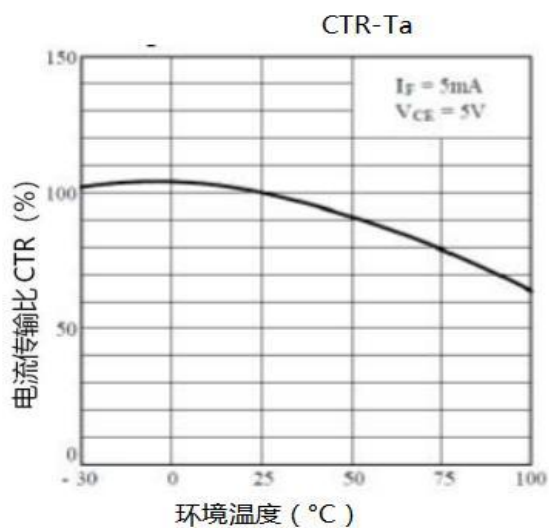
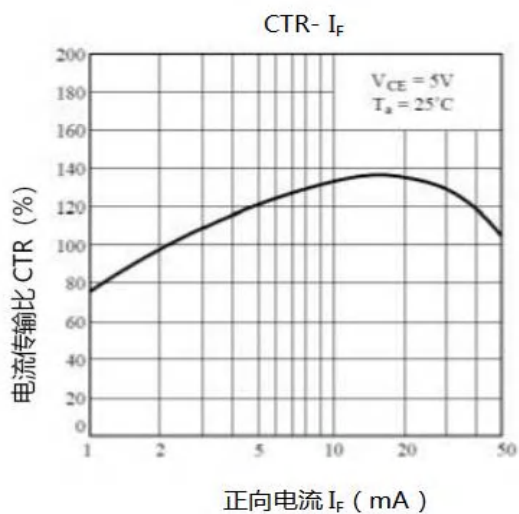
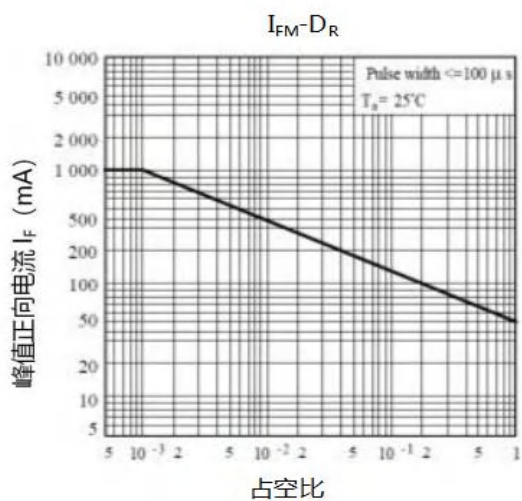
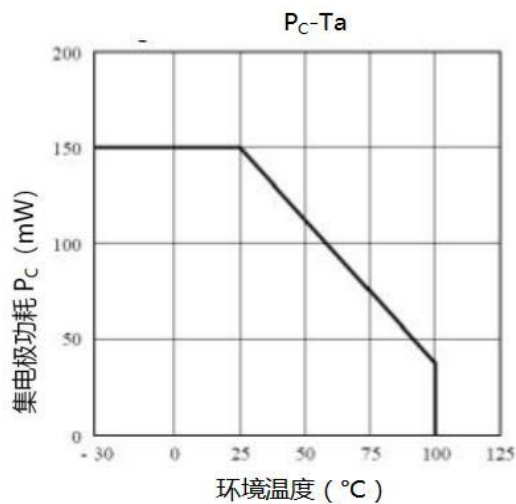
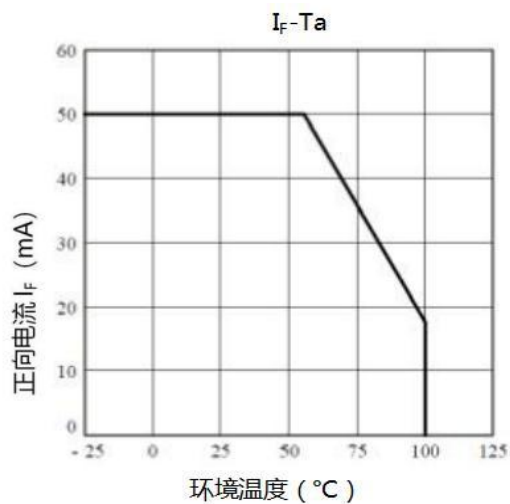
电流转换比 $CTR = I_C / I_F \times 100\%$

型号	分级标准	$I_C(\text{mA})$		对应 CTR (%)	
		$I_F = 5\text{mA}, V_{CE} = 5\text{V}, T_a = 25^\circ\text{C}$		$I_F = 5\text{mA}, V_{CE} = 5\text{V}, T_a = 25^\circ\text{C}$	
		Min	Max	Min	Max
EL357	Blank	2.5	30.0	50	600
	A	4.0	8.0	80	160
	B	6.5	13.0	130	260
	C	10.0	20.0	200	400
	D	15.0	30.0	300	600
	A or B	4.0	13.0	80	160
	B or C	6.5	20.0	130	400
	C or D	10.0	30.0	200	600
	A,B or C	4.0	20.0	80	400
	B,C or D	6.5	30.0	130	600
	A,B,C or D	4.0	30.0	80	600

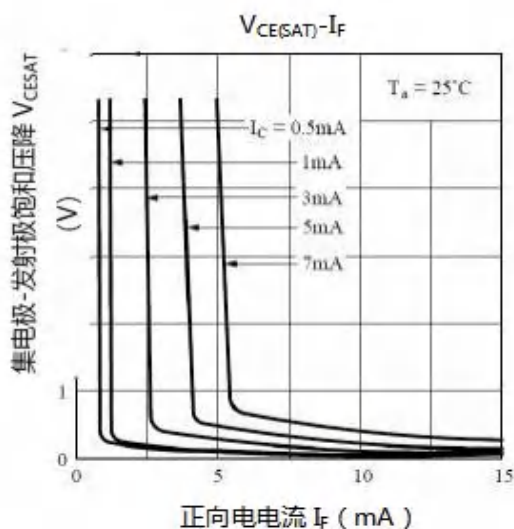
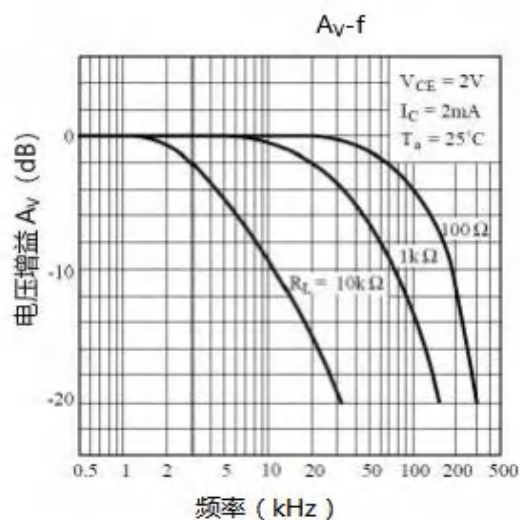
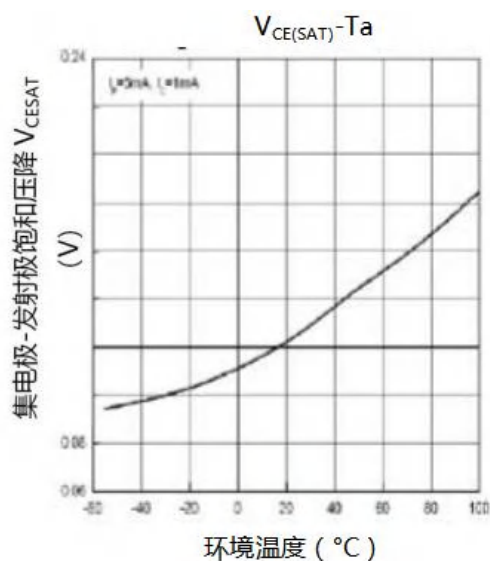
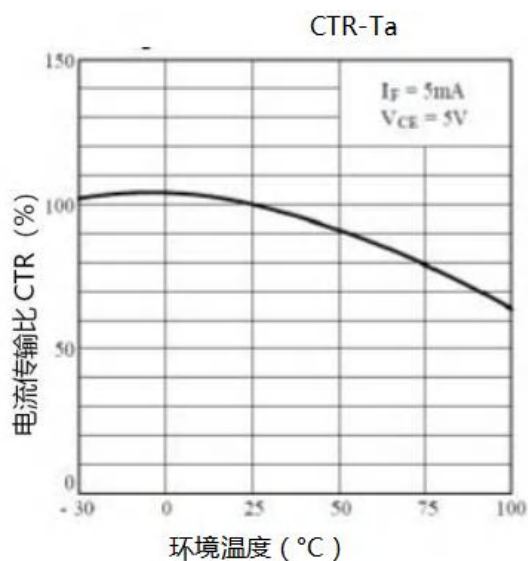
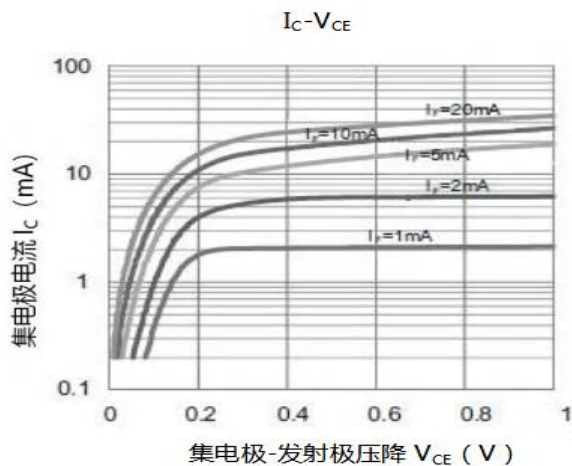
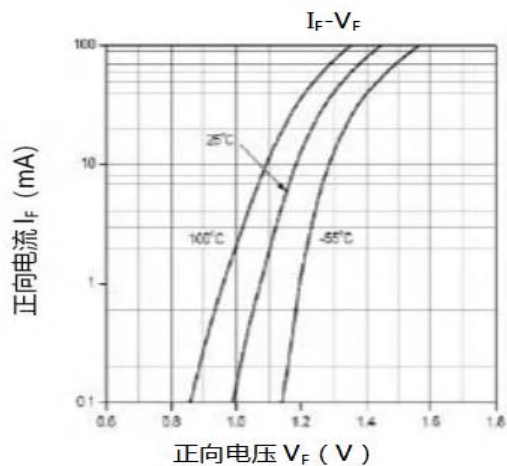
Test Circuit



RATING AND CHARACTERISTIC CURVES

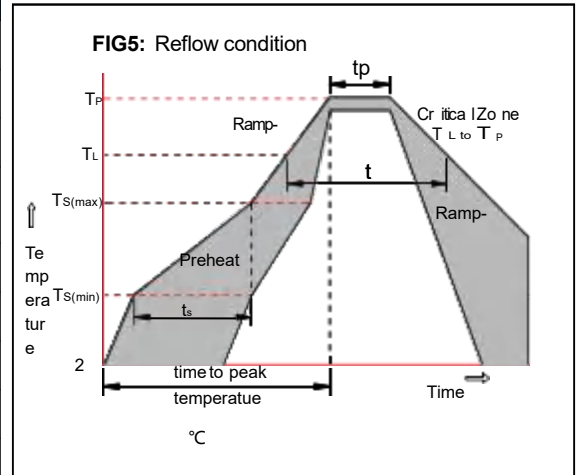


RATING AND CHARACTERISTIC CURVES

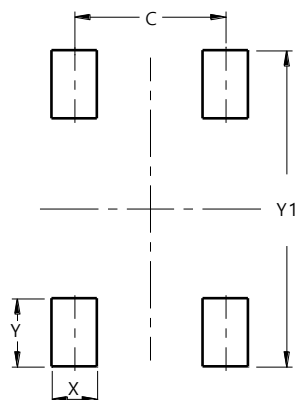
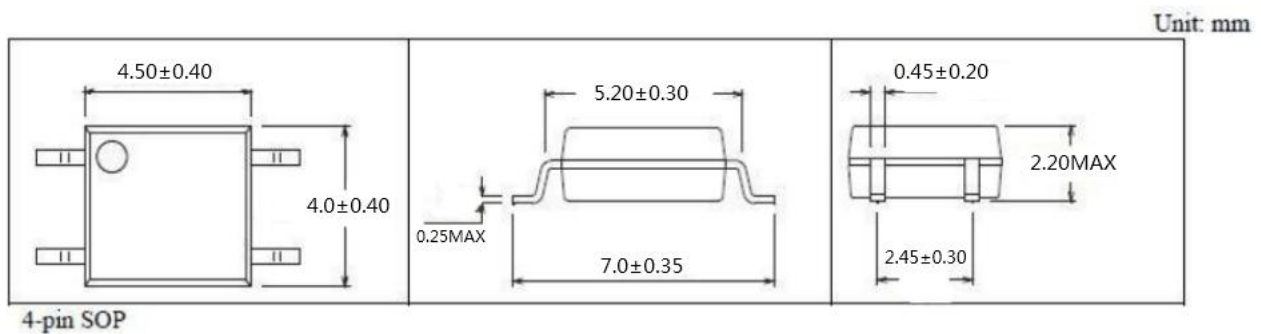


Soldering parameters

Reflow Condition		Pb-Free assembly (see as bellow)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150 °C
	-Temperature Max($T_{s(max)}$)	+200 °C
	-Time (Min to Max) (t_s)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3 °C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3 °C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217 °C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5) °C
Time within 5 °C of actual Peak Temp (t_P)		30 secs. Max
Ramp-down Rate		6 °C/sec. Max
Time 25 °C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260 °C



Package Dimensions & Suggested Pad Layout



Dimensions	Value (in mm)
C	2.45
X	0.80
Y	1.45
Y1	7.80